捷多邦,专业PCBI**SN54AH©T中39等SN7**4AHCT139 DUAL 2-LINE TO 4-LINE DECODERS/DEMULTIPLEXERS

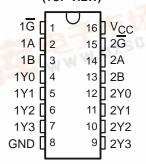
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- Inputs Are TTL-Voltage Compatible
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Incorporate Two Enable Inputs to Simplify Cascading and/or Data Reception
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

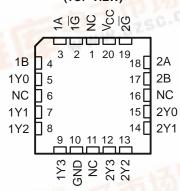
description/ordering information

The 'AHCT139 devices are dual 2-line to 4-line decoders/demultiplexers designed for 4.5-V to 5.5-V V_{CC} operation. These devices are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When used with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

SN54AHCT139 . . . J OR W PACKAGE SN74AHCT139 . . . D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AHCT139 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
212	PDIP – N	Tube	SN74AHCT139N	SN74AHCT139N
	SOIC – D	Tube	SN74AHCT139D	AHCT139
-40°C to 85°C	3010 - 15	Tape and reel	SN74AHCT139DR	ALICTISS
	SOP – NS	Tape and reel	SN74AHCT139NSR	AHCT139
	SSOP – DB	Tape and reel	SN74AHCT139DBR	HB139
	TSSOP – PW	Tube	SN74AHCT139PW	HB139
	1330F = FW	Tape and reel	SN74AHCT139PWR	110139
	TVSOP - DGV	Tape and reel	SN74AHCT139DGVR	HB139
- C	CDIP - J	Tube	SNJ54AHCT139J	SNJ54AHCT139J
-55°C to 125°C	CFP – W	Tube	SNJ54AHCT139W	SNJ54AHCT139W
2 12 A	LCCC – FK	Tube	SNJ54AHCT13FK	SNJ54AHCT139FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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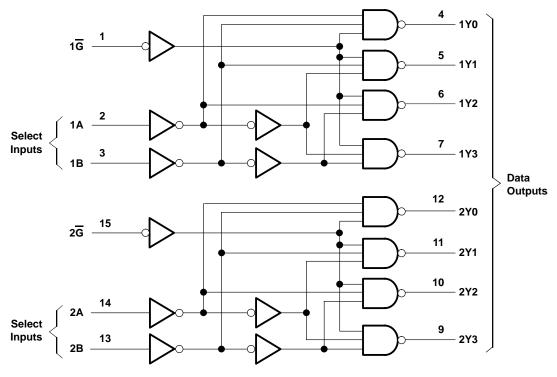
description/ordering information (continued)

The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. These decoders/demultiplexers feature fully buffered inputs, each of which represents only one normalized load to its driving circuit.

FUNCTION TABLE (each decoder/demultiplexer)

	INPUTS			OUT	DUTE		
G	SELECT		OUTPUTS				
9	В	Α	Y0	Y1	Y2	Y3	
Н	Х	Х	Н	Н	Н	Н	
L	L	L	L	Н	Н	Н	
L	L	Н	Н	L	Н	Н	
L	Н	L	Н	Н	L	Н	
L	Н	Н	Н	Н	Н	L	

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Note 1)		. -0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	c)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ _{JA} (see Note 2)		
-	DB package	82°C/W
	DGV package	120°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{sta}	. •	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54AHCT139		SN74AH	CT139	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	2	2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	5.5	0	5.5	V
٧o	Output voltage	0	VCC	0	VCC	V
loh	High-level output current	27/	-8		-8	mA
loL	Low-level output current	70 ₂	8		8	mA
Δt/Δν	Input transition rise or fall rate	d	20		20	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T _A = 25°C			SN54AHCT139		SN74AHCT139		UNIT
PARAMETER	TEST CONDITIONS	v _{CC}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
\/o	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4		V
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8	, A	3.8		v
V/01	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36	40	0.44		0.44	V
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	6	±1*		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2	30	20		20	μΑ
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35	Oka	1.5		1.5	mA
C _i	$V_I = V_{CC}$ or GND	5 V		2	10		, i		10	pF

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T	\ = 25°C	;	SN54AH	CT139	SN74AH	CT139	UNIT					
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT					
t _{PLH}	A or B	Y	C: - 15 pE		5**	7.2**	1**	8.5**	1	8.5	ns					
^t PHL	AOIB	l ^t	ı	CL = 15 pr	C _L = 15 pF		5**	7.2**	1**	8.5**	1	8.5	115			
^t PLH	IG	Y	C _L = 15 pF		4.4**	6.3**	1**	7.5**	1	7.5	ns					
t _{PHL}	5	,	·	•	•	•	OL = 13 pr	OL = 10 pi		4.4**	6.3**	1** 0	7.5**	1	7.5	110
tPLH	A or B	Y	C 50 pF		6.5	9.2	1	10.5	1	10.5	20					
t _{PHL}	AUB	ľ	Y	Y	Y	Y	Ť	Y $C_L = 50 \text{ pF}$		6.5	9.2	Q1	10.5	1	10.5	ns
t _{PLH}	IG	Υ	C 50 pE		5.9	8.3	Q 1	9.5	1	9.5	ns					
^t PHL	9	ſ	$C_L = 50 \text{ pF}$		5.9	8.3	1	9.5	1	9.5	115					

^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

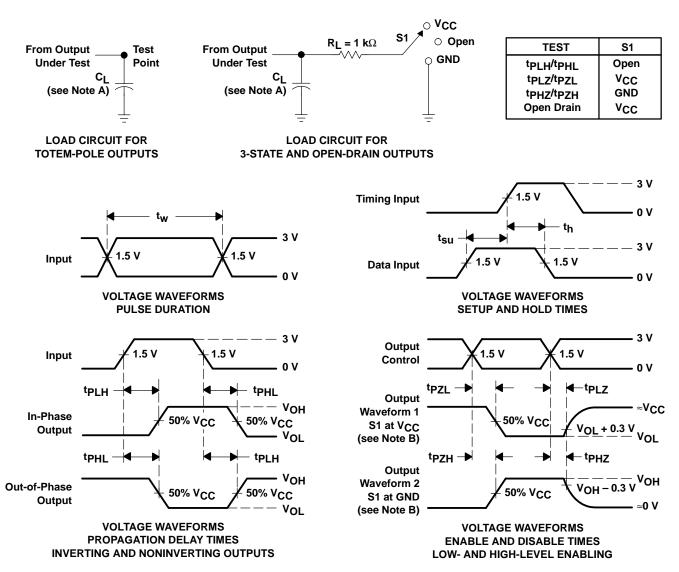
PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	13	pF



[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or VCC.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







9-Aug-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCT139D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI
SN74AHCT139DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT139NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHCT139NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74AHCT139PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT139PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

9-Aug-2005

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



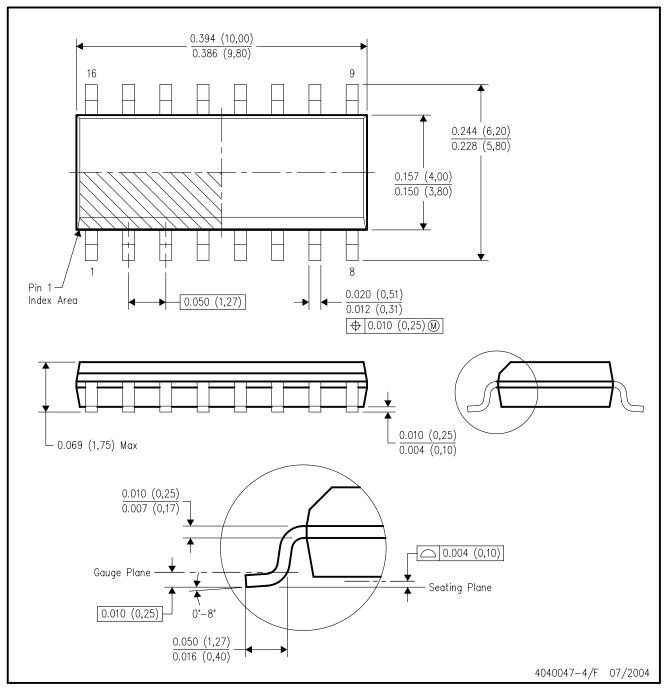
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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